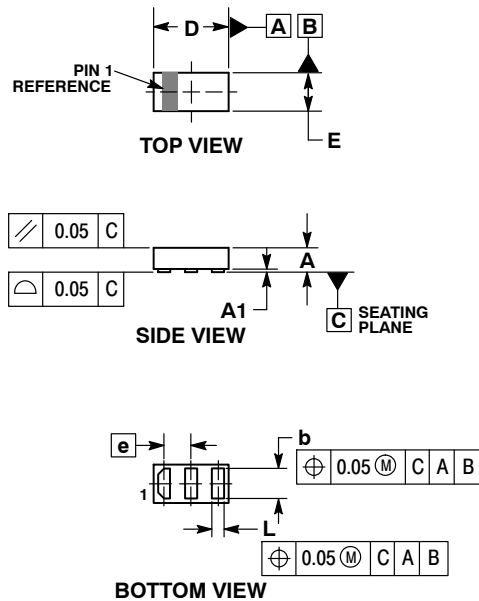




SCALE 8:1

X4DFN3 0.62x0.32, 0.225P
CASE 718AB
ISSUE A

DATE 13 MAR 2018



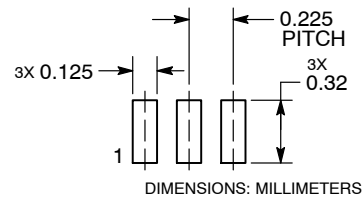
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.

MILLIMETERS			
DIM	MIN	NOM	MAX
A	0.175	0.20	0.225
A1	0.000	0.015	0.030
b	0.23	0.25	0.27
D	0.595	0.620	0.645
E	0.295	0.320	0.345
e	0.225 BSC		
L	0.08	0.10	0.12

GENERIC MARKING DIAGRAMS*


X = Specific Device Code

RECOMMENDED MOUNTING FOOTPRINT*


See Application Note AND8398/D for more mounting details

*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	X4DFN3 0.62x0.32, 0.225P	PAGE 1 OF 1

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